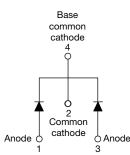
Vishay Semiconductors

HEXFRED[®] Ultrafast Soft Recovery Diode, 2 x 8 A



www.vishay.com



PRIMARY CHARACTERISTICS						
I _{F(AV)}	2 x 8 A					
V _R	600 V					
V _F at I _F	1.4 V					
t _{rr} typ.	18 ns					
T _J max.	150 °C					
Package	3L TO-220AB					
Circuit configuration	Common cathode					

FEATURES

- Ultrafast and ultrasoft recovery
- Very low I_{RRM} and Q_{rr}
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

BENEFITS

- Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

VS-HFA16TA60C... is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 8 A per leg continuous current, the VS-HFA16TA60C... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to "snap-off" during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA16TA60C... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Cathode to anode voltage	V _R		600	V		
Maximum continuous forward currentper leg	I	T _C = 100 °C	8	А		
per device	- I _F	1C = 100 C	16			
Single pulse forward current	I _{FSM}		60	A		
Maximum repetitive forward current	I _{FRM}		24			
Maximum neuror dissinction	PD	T _C = 25 °C	36	W		
Maximum power dissipation		T _C = 100 °C	14	vv		
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +150	°C		

Revision: 02-Apr-2019

1

Document Number: 96203

For technical questions within your region: <u>DiodesAmericas@vishay.com</u>, <u>DiodesAsia@vishay.com</u>, <u>DiodesEurope@vishay.com</u> THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT <u>www.vishay.com/doc?91000</u>



FREE



www.vishay.com

Vishay Semiconductors

ELECTRICAL SPECIFICATIONS PER LEG ($T_J = 25 \text{ °C}$ unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS	
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 μA		600	-	-		
	I _F = 8 A			See fig. 1	-	1.4	1.7	V
Maximum forward voltage	V _{FM}	I _F = 16 A	-		1.7	2.1		
		I _F = 8 A, T _J = 125 °C	-		1.4	1.7		
Maximum reverse	l	$V_{R} = V_{R}$ rated	See fig. 2	-	0.3	5.0		
leakage current	kage current		See lig. 2	-	100	500	μA	
Junction capacitance	CT	V _R = 200 V	See fig. 3	-	10	25	pF	
Series inductance	L _S	Measured lead to lead 5 mm from p	ackage body	-	8.0	-	nH	

DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	ONDITIONS	MIN.	TYP.	MAX.	UNITS	
	t _{rr}	$I_F = 1.0 \text{ A}, dI_F/dt = 200$) A/µs, V _R = 30 V	-	18	-		
Reverse recovery time See fig. 5 and fig. 10	t _{rr1}	T _J = 25 °C		-	37	55	ns	
	t _{rr2}	T _J = 125 °C		-	55	90		
Peak recovery current	I _{RRM1}	T _J = 25 °C	I _F = 8.0 A dI _F /dt = 200 A/μs V _R = 200 V	-	3.5	5.0	А	
See fig. 6	I _{RRM2}	T _J = 125 °C		-	4.5	8.0	A	
Reverse recovery charge	Q _{rr1}	T _J = 25 °C		-	65	138	nC	
See fig. 7	Q _{rr2}	T _J = 125 °C		-	124	360	no	
Peak rate of fall recovery current during t _b See fig. 8	dl _{(rec)M} /dt1	T _J = 25 °C		-	240	-		
	dl _{(rec)M} /dt2	T _J = 125 °C		-	210	-	A∕µs	

THERMAL - MECHANICAL SPECIFICATIONS PER LEG								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C		
Junction to case, single leg conducting	Р		-	-	3.5			
Junction to case, both legs conducting	R _{thJC}		-	-	1.75	κ/w		
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	80			
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.5	-			
Weight			-	2.0	-	g		
weight			-	0.07	-	oz.		
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)		
Marking device		Case style 3L TO-220AB		HFA16	TA60C			



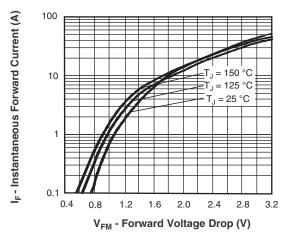


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

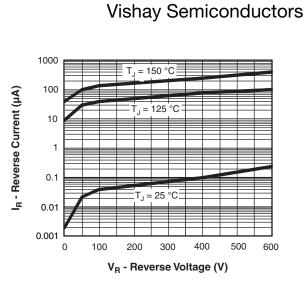


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

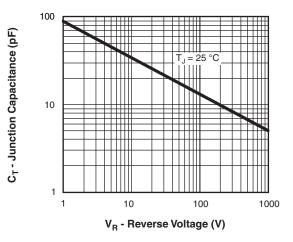


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

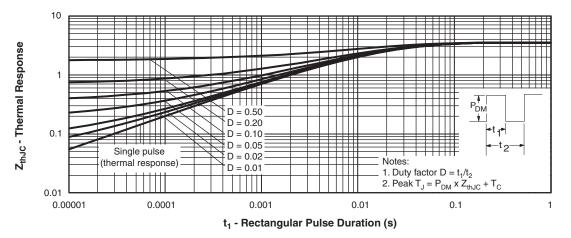


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

 Revision: 02-Apr-2019
 3
 Document Number: 96203

 For technical questions within your region: DiodesAmericas@vishay.com, DiodesAsia@vishay.com, DiodesEurope@vishay.com
 THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT www.vishay.com/doc?91000



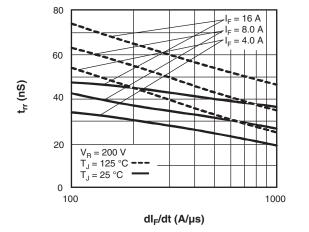


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt (Per Leg)

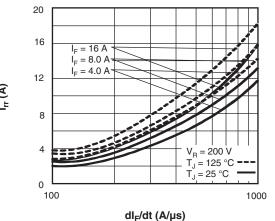
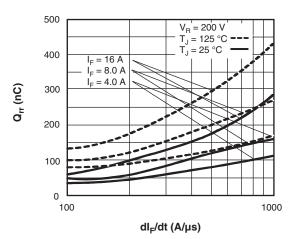


Fig. 6 - Typical Recovery Current vs. dl_F/dt (Per Leg)



VS-HFA16TA60C-M3

Vishay Semiconductors

Fig. 7 - Typical Stored Charge vs. dl_F/dt (Per Leg)

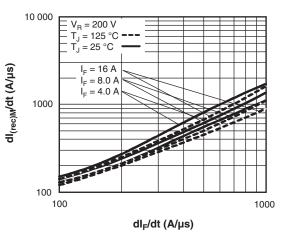


Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt (Per Leg)

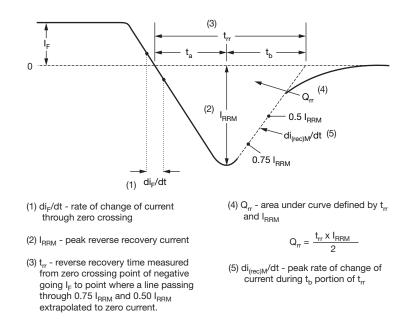


Fig. 9 - Reverse Recovery Waveform and Definitions

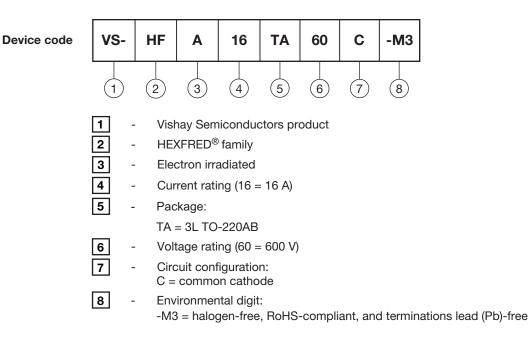
Revision: 02-Apr-2019	4	Document Number: 96203
For technical questions within your region:	DiodesAmericas@vishay.com, DiodesAsia@vishay.com, DiodesAsiaw.com, DiodesAsiaw.com, DiodesAsiaw.com, DiodesAsiaw.com, DiodesAsiaw.com, DiodesAsiaw.com, DiodesAsiaw.com, DiodesAsiaw.com, DiodesAsiaw.com, Dio	hay.com, DiodesEurope@vishay.com
	E WITHOUT NOTICE. THE PRODUCTS DESCR	
ARE SUBJECT TO SPEC	CIFIC DISCLAIMERS, SET FORTH AT <u>www.visha</u>	<u>ay.com/doc?91000</u>

Vishay Semiconductors



www.vishay.com

ISHAY



ORDERING INFORMATION (Example)								
PREFERRED P/N	PREFERRED P/N QUANTITY PER T/R MINIMUM ORDER QUANTITY PACKAGING DESCRIPTION							
VS-HFA16TA60C-M3	50	1000	Antistatic plastic tube					

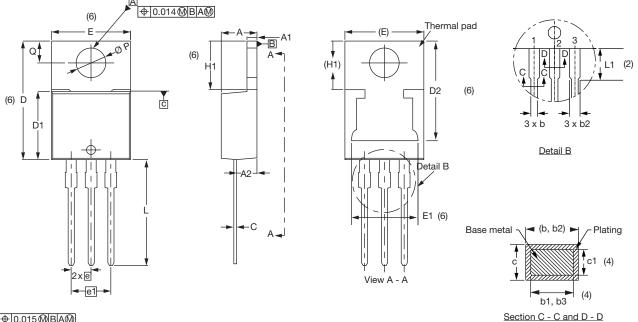
LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?96154			
Part marking information	www.vishay.com/doc?95028			
SPICE model	www.vishay.com/doc?96596			



Vishay Semiconductors

3L TO-220AB

DIMENSIONS in millimeters and inches



⊕0.015@BA@





SYMBOL	MILLIN	ILLIMETERS INCHES		NOTES		
STINDUL	MIN.	MAX.	MIN.	MAX.	NOTES	
А	4.25	4.65	0.167	0.183		
A1	1.14	1.40	0.045	0.055		
A2	2.50	2.92	0.098	0.115		
b	0.69	1.01	0.027	0.040		
b1	0.38	0.97	0.015	0.038	4	
b2	1.20	1.73	0.047	0.068		
b3	1.14	1.73	0.045	0.068	4	
С	0.36	0.61	0.014	0.024		
c1	0.36	0.56	0.014	0.022	4	
D	14.85	15.35	0.585	0.604	3	
D1	8.38	9.02	0.330	0.355		

_		
Conforms to JEDEC [®]	outline	TO-220AB

SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STINDOL	MIN.	MAX.	MIN.	MAX.	NOTES
D2	11.68	13.30	0.460	0.524	6, 7
Ш	10.11	10.51	0.398	0.414	3, 6
E1	6.86	8.89	0.270	0.350	6
е	2.41	2.67	0.095	0.105	
e1	4.88	5.28	0.192	0.208	
H1	6.09	6.48	0.240	0.255	6
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
ØР	3.54	3.91	0.139	0.154	
Q	2.60	3.00	0.102	0.118	

Notes

⁽²⁾ Lead dimension and finish uncontrolled in L1

- ⁽⁴⁾ Dimension b1, b3, and c1 apply to base metal only
- (5) Controlling dimensions: inches
- ⁽⁶⁾ Thermal pad contour optional within dimensions E, H1, D2, and E1
- ⁽⁷⁾ Outline conforms to JEDEC[®] TO-220, except D2

Revision: 13-Jun-2019

 $^{^{(1)}\,}$ Dimensioning and tolerancing as per ASME Y14.5M-1994

⁽³⁾ Dimension D, D1, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body



Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.